

IN THE UNITED STATES PATENT AND TRADEMARK OFFICE

In re Patent No.: 7,190,061
Inventor: Dong-Ho LEE
Issued: March 13, 2007
Ser. No.: 10/750,979 Filed: January 2, 2004
Group Art Unit: 2814 Examiner: Thao X. LE
For: STACK PACKAGE MADE OF CHIP SCALE PACKAGES

Commissioner for Patents
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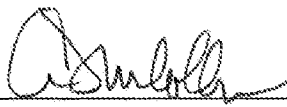
MINOR CORRECTIONS LETTER

In checking the subject original Letters Patent with our copy of the application, the following errors which occurred in the printing of the patent were noted:

Column 5, line 59, the words "claim 1" should read -- claim 1, --.

Since these are minor errors, we are not requesting the issuance of a Certificate of Correction. However, it is requested that this letter be made of record in the file of the patent.

Respectfully submitted,
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